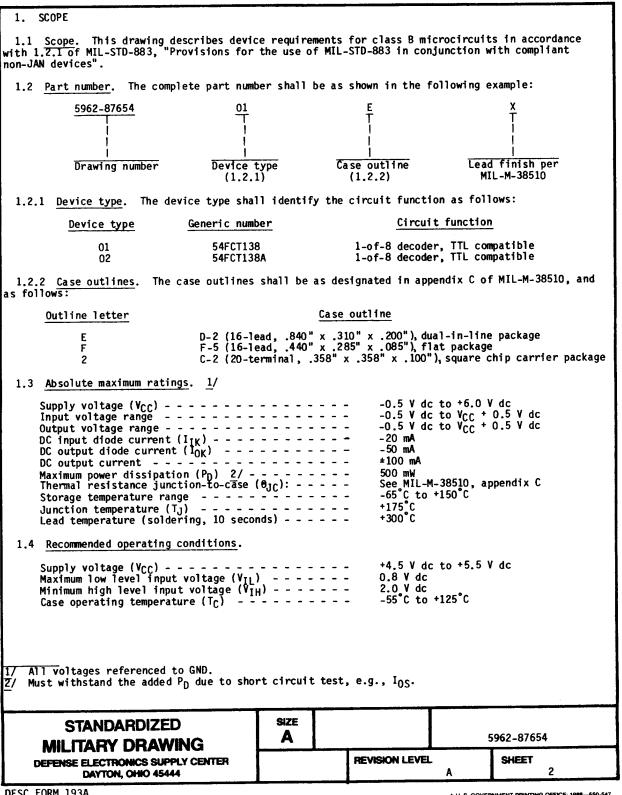
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DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.



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## 2. APPLICABLE DOCUMENTS

2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

**SPECIFICATION** 

MILITARY

MIL-M-38510

- Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883

Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

- 2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.
  - 3. REQUIREMENTS
- 3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- $3.2~\underline{\text{Design}}$ , construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
  - 3.2.1 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.
  - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.
  - 3.2.3 Truth table. The truth table shall be as specified on figure 2.
  - 3.2.4 Logic diagram. The logic diagram shall be as specified on figure 3.
- 3.3 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full case operating temperature range.
- 3.4 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.4 herein.
- 3.5 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.

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DESC FORM 193A SEP 87 TABLE I. Electrical performance characteristics. Limits Device Unit Symbol Conditions |Group A Test -55°C < T<sub>C</sub> < +125°C V<sub>CC</sub> = 5.0 V dc ±10% |subgroups| Min Max types unless otherwise specified 4.3 ٧  $V_{CC} = 4.5 \text{ V}$  $I_0 = -300 \mu A$ A11 1, 2, 3 VOH High level output | VIL = 0.8 V voltage VIH = 2.0 V ٧ 2.4 1, 2, 3 A11  $I_0 = -12 \text{ mA}$ 0.2 ٧ A1 1 1, 2, 3  $V_{CC} = 3.0 \text{ V}$  $I_0 = 300 \mu A$ Low level output  $IV_{OL}$ | VIL = 0.8 V voltage IVIH = 2.0 V IVCC = 4.5 V 1, 2, 3 0.5  $I_0 = 32 \text{ mA}$ A1 1 VIL = 0.8 V ٧ -1.2 Input clamp voltage  $V_{CC} = 4.5 \text{ V}, I_{IN} = -18 \text{ mA}$ A11 1 VIK 5.0 High level input  $V_{CC} = 5.5 \text{ V}, V_{IN} = 5.5 \text{ V}$ A1 1 1, 2, 3 μA IIH current Low level input A11 1, 2, 3 -5.0 μA  $V_{CC} = 5.5 \text{ V}, V_{IN} = GND$ IIL current A11 1, 2, 3 | -60 mΑ  $V_{CC} = 5.5 \text{ V}$ Short circuit 1/ los output current  $|V_{IN}| \le 0.2 \text{ V or } V_{IN} \ge 5.3 \text{ V}$  $|V_{CC}| = 5.5 \text{ V, } f_I = 0 \text{ MHz}$ 1.5 mΑ A11 1, 2, 3 Quiescent power ICCQ supply current (CMOS inputs) V<sub>CC</sub> = 5.5 V, V<sub>IN</sub> = 3.4 V 1, 2, 3 2.0 mΑ A11 Quiescent power VICC. supply current (TTL inputs) 2/ 0.3 mA/MHz  $|V_{CC} = 5.5 V$ , Outputs open, A11 3/ Dynamic power ICCD supply current 10ne input toggling |50% duty cycle | $V_{IN} \ge 5.3$  V or  $V_{IN} \le 0.2$  V See footnotes at end of table. SIZE STANDARDIZED A 5962-87654 **MILITARY DRAWING REVISION LEVEL** SHEET DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444

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TABL	E I. <u>Ele</u>	ectrical performance characteris	tics - C	ontinued.			
Test	  Symbol   		  Device  types 	Group A  subgroups  	Limi	ts Max	Unit
Total power 4/ supply current	Icc	$ \begin{array}{l}   \text{V}_{\text{IN}} \geq 5.3 \text{ V or V}_{\text{IN}} < 0.2 \text{ V} \\   \text{V}_{\text{CC}} = 5.5 \text{ V, f}_{\text{I}} = 10 \text{ MHz,} \\   \text{One bit toggling} = 50\% \text{ duty} \\   \text{cycle} \\ \end{array} $	   All   	1, 2, 3	] 	4.5	mA
	   	$ V_{IN}  = 3.4 \text{ V or } V_{IN} = \text{GND}$ $ V_{CC}  = 5.5 \text{ V, } f_I = 10 \text{ MHz,}$ $ V_{CC}  = 10 \text{ MHz,}$	01	1, 2, 3	[	5.3	
	 	One bit toggling - 50% duty  cycle 	02			5.5	
Functional tests	]   		A11	7, 8		   	
Input capacitance	IC <sub>IN</sub>		All	4	1	10	pF
Output capacitance	COUT	See 4.3.1c	A11	   4 	! 	12	pF
Propagation delay time $A_0$ to $\overline{0}_n$	tpLH1,	$C_L = 50 \text{ pF } \pm 10\%$   $R_L = 500\Omega \pm 5\%$	01	9,10,11	1.0	12.0	l ns
		See figure 4		 	1.0	7.8	   
Propagation delay time E <sub>1</sub> or E <sub>2</sub> to O <sub>n</sub>	  tpLH2,  tpHL2	-    -	01	9,10,11	1.0	12.5	l ns
<b>.</b>			02	   	1.0	8.0	
Propagation delay time E3 to O <sub>n</sub>	T  tpLH3,  tpHL3	-    -	01	9,10,11	1.0	12.5	l ns
			02	   	1.0	8.0	 

<sup>1/</sup> Not more than one output should be shorted at one time and the duration of the short circuit

condition should not exceed 1 second. In accordance with TTL driven input ( $V_{\rm IN}$  = 3.4 V); all other inputs at  $V_{\rm CC}$  or GND. This parameter is not directly testable but is derived for use in total power supply

calculations.  $I_{CC} = I_{CCQ} + (\Delta I_{CC} \times D_H \times N_T) + I_{CCD} (f_I \times N_I)$ 

where  $D_H$  = Duty cycle for TTL inputs high  $N_T$  = Number of TTL inputs at  $D_H$  fI = Input frequency in MHz

 $N_{I}$  = Number of inputs at  $f_{I}$ 

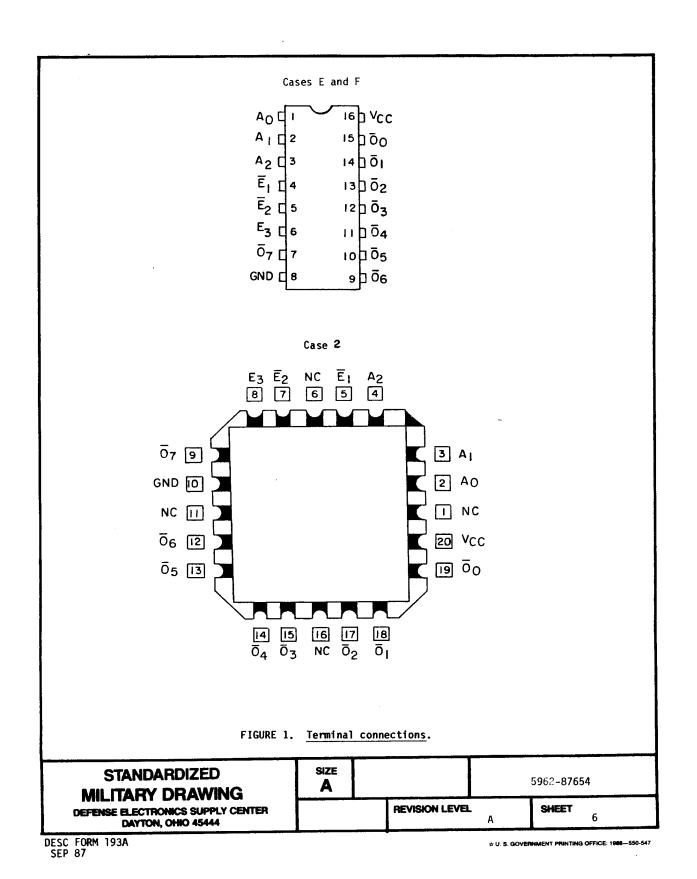
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**Outputs** Inputs  $\bar{o}_0$   $\bar{o}_1$   $\bar{o}_2$   $\bar{o}_3$   $\bar{o}_4$   $\bar{o}_5$   $\bar{o}_6$   $\bar{o}_7$ E1 E2 E3 A<sub>0</sub> A<sub>1</sub> A<sub>2</sub> I **нинини** ни H X X  $X \quad X \quad X$ н и и и и и и  $X \quad X \quad X$ X H X **нинини** н  $X \quad X \quad X$ X X L LHHHHHHHH LLH LLL **H L H H H H H** L L H H L L **H H L H H H H H** LHL LLH HHHLHHHH H H L LLH HHHHLHHH LLH LLH HHHHHLHH H L H LLH іннинници LHH LLH IN H H H H H L LLH н н н

FIGURE 2. Truth table.

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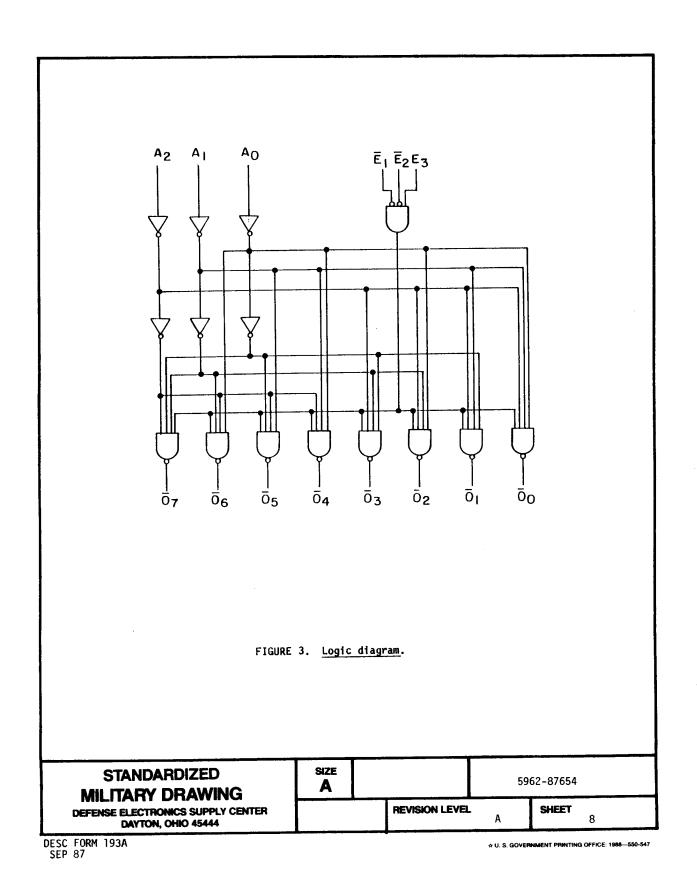
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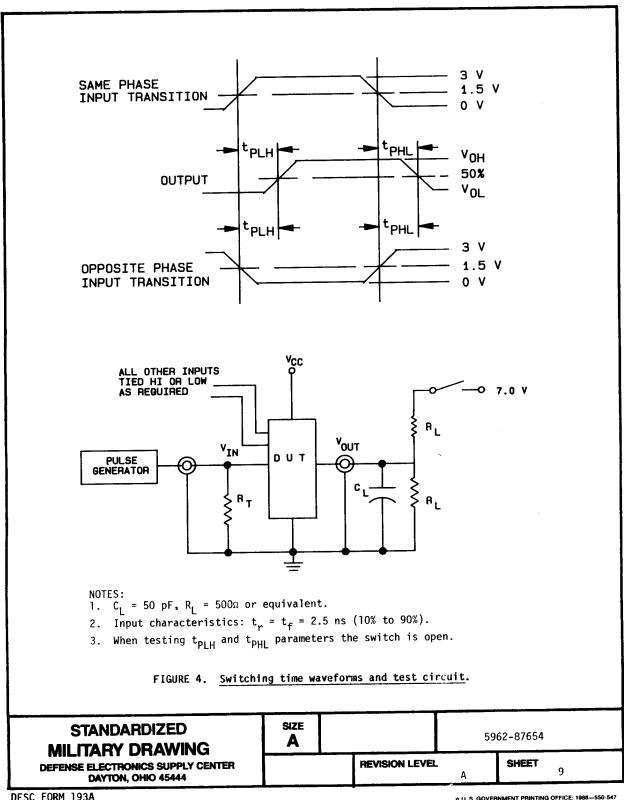
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- 3.7 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-SID-883 (see 3.1 herein).
- 3.8 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
  - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
  - a. Burn-in test, method 1015 of MIL-STD-883.
    - Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
    - (2)  $T_A = +125^{\circ}C$ , minimum.
  - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
  - 4.3.1 Group A inspection.
    - a. Tests shall be as specified in table II herein.
    - b. Subgroups 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
    - c. Subgroup 4 ( $C_{\rm IN}$  and  $C_{\rm OUT}$  measurements) shall be measured only for the initial test and after process or design changes which may affect capacitance. Test all applicable pins on 5 devices with zero failures.
    - d. Subgroups 7 and 8 tests shall verify the truth table on figure 2.
  - 4.3.2 Groups C and D inspections.
    - a. End-point electrical parameters shall be as specified in table II herein.
    - b. Steady-state life test conditions, method 1005 of MIL-STD-883:
      - (1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).
      - (2)  $T_A = +125^{\circ}C$ , minimum.
      - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

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## TABLE II. Electrical test requirements.

	Subgroups
MIL-STD-883 test requirements	(per method
	5005, table I)
Interim electrical parameters   (method 5004) 	
Final electrical test parameters	1*, 2, 3, 7,
(method 5004)	8, 9, 10, 11
Group A test requirements	1, 2, 3, 4, 7, 1
(method 5005)	8, 9, 10, 11
Groups C and D end-point   electrical parameters   (method 5005)	1, 2, 3

<sup>\*</sup> PDA applies to subgroup 1.

## 5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

## 6. NOTES

- 6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone  $513-\overline{2}96-5375$ .

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6.4 Approved source of supply. An approved source of supply is listed herein. Additional sources will be added as they become available. The vendor listed herein has agreed to this drawing and a certificate of compliance (see 3.5 herein) has been submitted to DESC-ECS.

Military drawing   part number	Vendor     CAGE     number	Vendor   similar part   number <u>1</u> /
5962-8765401EX	61772	IDT54FCT138DB
5962-8765401FX	61772	IDT54FCT138EB
5962-87654012X	61772	IDT54FCT138LB
5962-8765 <b>4</b> 02EX	61772	IDT54FCT138ADB
5962-8765402FX	61772	IDT54FCT138AEB
5962-87654022X	61772	IDT54FCT138ALB

1/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

61772

Vendor name and address

Integrated Device Technology 3236 Scott Boulevard Santa Clara, CA 95052

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